

Attorney Docket No. 108298532US1 Disclosure No. 00-0120.01

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U.S. Patent and Trademark Office, U.S. DEPARTMENT OF COMMERCE

10/620,714

July 15, 2003

David J. Corisis

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Application Number

First Named Inventor

Filing Date

(to be used for all correspondence after initial filing) Art Unit			2833			
		Examiner Name				
Total Number of Pages in This Submission		5*	Attorney Docket Number	108298532US1		
ENGLOSUBES (C) 1 HII 1 1 1 1 1						
Fee Transmittal Form Fee Attached Amendment/Reply After Final Affidavits/declaration(s) Extension of Time Request Express Abandonment Request Information Disclosure Statement Certified Copy of Priority Document(s) Response to Missing Parts/ Incomplete Application		Drawing(s) □ Licensing-related Papers □ Petition □ Petition to Convert to a Provisional Application □ Power of Attorney, Revocation Change of Correspondence Address □ Terminal Disclaimer □ Request for Refund □ CD, Number of CD(s) Remarks		After Allowance communication to Group Appeal Communication to Board of Appeals and Interferences Appeal Communication to Group (Appeal Notice, Brief, Reply Brief) Proprietary Information Status Letter Other Enclosures Cited References (2): Return Receipt Postcard		
Response to Missing Parts under 37 CFR 1.52 or 1.53						
SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT						
Firm or Individual name John M. Wechkin Registration No. 42,216						
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This collection of information is required by 37 CFR 1.5. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

DAVID J. CORISIS

EXAMINER:

(TO BE ASSIGNED)

APPLICATION NO.:

10/620,714

ART UNIT:

2833

FILED:

JULY 15, 2003

CONF. NO:

9586

For:

STACKED MICROELECTRONIC DIES AND METHODS FOR STACKING

MICROELECTRONIC DIES

<u>Information Disclosure Statement Within Three Months of</u>
<u>Application Filing or Before First Action – 37 C.F.R. § 1.97(b)</u>

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

1. Timing of Submission

This information disclosure is being filed within three months of the filing date of this application or date of entry into the national stage of an international application or before the mailing date of a first Office action on the merits, whichever occurs last [37 C.F.R. § 1.97(b)]. The references listed on the enclosed Form PTO-1449 (modified) may be material to the examination of this application; the Examiner is requested to make them of record in the application.

2. Cited Information

\boxtimes	Copie	Copies of the following references are enclosed:						
		All cited references References marked by two asterisks (**)						
	•	es of the following references can be found in parent U.S. Application 9/644,766:						
		All cited references References not marked by two asterisks						

3. Effect of Information Disclosure Statement (37 C.F.R. § 1.97(h))

before the mailing date of the first Office Action.

statement.

This Information Disclosure Statement is not to be construed as a representation that: (i) a search has been made; (ii) additional information material to the examination of this application does not exist; (iii) the information, protocols, results and the like reported by third parties are accurate or enabling; or (iv) the cited information is, or is considered to be, material to patentability. In addition, applicant does not admit that any enclosed item of information constitutes prior art to the subject invention and specifically reserves the right to demonstrate that any such reference is not prior art.

No fees are believed due because this Information Disclosure Statement is being filed

4. Fee Payment

	ant further submits that no fee is due in light of the following certification 37 C.F.R. § 1.97(e) (check only one):
	In accordance with 37 C.F.R. § 1.97(e)(1), the undersigned hereby states that each item of information submitted herewith was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement; or
	In accordance with 37 C.F.R. § 1.97(e)(2), the undersigned hereby states that no item of information submitted herewith was cited in a communication from a foreign patent office in a counterpart foreign application, or, to the knowledge of the person signing the certification after making reasonable inquiry, was known to any individual designated

However, should the Commissioner determine that fees are due in order for this Information Disclosure Statement to be considered, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 50-0665.

Date: HOV . 12, 7003

Perkins Coie LLP

Respectfully submitted,

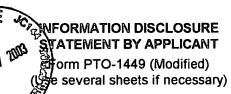
John M. Wechkin

in 37 C.F.R. § 1.56(c), more than three months prior to the filing of this

Registration No. 42,216

Correspondence Address:

Customer No. 25096
Perkins Coie LLP
P.O. Box 1247
Seattle, Washington 98111-1247
(206) 359-8000



of

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COMPLETE IF KNOWN					
Application Number	10/620,714				
Confirmation Number	9586				
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First Named Inventor	David J. Corisis				
Group Art Unit	2833				
Examiner Name					
Attorney Docket No.	108298532US1				

		417	U	.S. PATENT DOCUMENTS		
Examiner Initials*	Cite No.		n (ind Code (if known)	Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
-		U.S. Application No. 09/634,056 (Attorney Docket No. 108298503US)		Jiang et al.	Filed 08/09/2000	
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EXAMINER		DATE CONSIDERED	-
*FXAMINER:	Initial if reference considered, whether or not criteria is in confo	rmance with MPEP 609.	Draw line through citation if not in conformance and

not considered. Include copy of this form with next communication to application(s)



INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Form PTO-1449 (Modified)

Subsection (Modified)

of

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COMPLETE IF KNOWN					
Application Number 10/620,714					
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Attorney Docket No.	108298532US1				

			U	S. PATENT DOCUMENTS			
Examiner Initials*	Cite No.	U.S. Patent or Application Kind Co		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Whe Relevant Passages or Relevant Figures Appear	ге
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-	**	6,560,117 E	32	Moon	05/06/2003		
		OTHER PRIOR	ARI	-NON PATENT LITERATURE D	OCUMENTS		
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume issue number(s), publisher, city and/or country where published.					
		"3-D IC Packaging." Semiconductor International, May 1998. http://www.semiconductor.net/semiconductor/archive/May98/docs/ind_news2.html .					
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EXAMINER		DATE CONSIDERED
*EXAMINER:	Initial if reference considered, whether or not criteria is in conference considered. Include copy of this form with next communic	ormance with MPEP 609. Draw line through citation if not in conformance and ation to application(s).